

L Number	Hits	Search Text	DB	Time stamp
1	55412	substrate near3 (ceramic alumina beryllia beo)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/07 16:09
2	6881	(substrate near3 (ceramic alumina beryllia beo)) and (semiconductor near1 (package device))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/07 16:11
3	328	((substrate near3 (ceramic alumina beryllia beo)) and (semiconductor near1 (package device))) and (direct\$2 adj (bonded bonding))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/07 16:12
4	430	((substrate near3 (ceramic alumina beryllia beo)) and (semiconductor near1 (package device))) and ((encapsulant sealing) near3 (epoxy resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/07 16:13
5	32	((substrate near3 (ceramic alumina beryllia beo)) and (semiconductor near1 (package device))) and (direct\$2 adj (bonded bonding)) and ((encapsulant sealing) near3 (epoxy resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/07 16:13
6	16	((substrate near3 (ceramic alumina beryllia beo)) and (semiconductor near1 (package device))) and ((encapsulant sealing) near3 (epoxy resin))) and ghz	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/07 16:16